



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re Application: Yeo, et al.

Art Unit: 2827

Serial No.: 10/078,718

Filed: February 19, 2002

For: **Enhanced Chip Scale Package For Wire Bond Dies**

Mail Stop DD

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

**INFORMATION DISCLOSURE STATEMENT**

In accordance with 37 C.F.R. 1.56, counsel wishes to make of record the attached items of information for the Examiner's consideration in connection with this application. Each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application mailed 30 June 2003, which is less than 3 months from this filing. Also enclosed is a form PTO-1449 for the Examiner's convenience in making such consideration of record. Inclusion herein of any particular item of information is not to be construed as an admission that same is prior art.

**The Commissioner is hereby authorized to charge any fees that may be required or credit any overpayment to Deposit Account 18-1167.**

08/11/2003 MAHMED1 00000082 10078718

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Respectfully submitted,

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**CERTIFICATE OF MAILING**

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Name of Depositor Deborah Mondello Signature  Date of Signature 8-6-03



FORM PTO-1449

Docket Number: 4795-002  
Serial Number: 10/078,718**INFORMATION DISCLOSURE CITATION  
IN AN APPLICATION PURSUANT TO  
37 CFR §1.97 & 1.98**Applicant: Yeo, et al.  
Filing Date: February 19, 2002  
Group: 2827**U. S. PATENT DOCUMENTS**

Examiner					Filing Date		
Initial		Patent No.	Date	Name	Class	Subcl	If Approp.
	A	5,468,999	1995	Lin et al.			

**FOREIGN PATENT DOCUMENTS**

					Translation		
		Patent No.	Date	Name	Class	Subcl	Yes No
	B	WO 98/48449	1998	Elenius et al.			

**OTHER DOCUMENTS** (including author, title, date, pages, etc.)


EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation not in conformance and not considered. Include copy of this form with next communication to the applicant.